FORM PTO-1449 (REV.7-80)

U.S. DEPARTMENT OF COMMERCE **附tent and trademark Office**

ATTY. DOCKET NO. 34091/US

APPLICATION NO. 10/783,662

INFORMATION DISCLOSURE STATEMENT
(Use Se LIMBERTS if necessary)

APPLICANT(S) Peter C. Salmon

FILING DATE

GROUP ART UNIT

February 20, 2004 2823 **U.S. PATENT DOCUMENTS** *EXAMINER DOCUMENT NUMBER DATE NAME CLASS SUBCLASS FILING DATE INITIAL IF APPROPRIATE 06/19/84 714 28 4,455,654 Bhaskar et al. AA 257 4,748,495 05/31/88 Kucharek 713 AB Bickford et al. AC 4,862,322 08/29/89 361 718 29 848 4,912,844 04/03/90 Parker ΑD 257 5,001,548 03/19/91 Iversen 714 ΑĖ 361 699 5,159,529 10/27/92 Lovgren 361 5,162,974 11/10/92 Currie 702 ΑG 438 73 05/25/93 Cayson et al. 5,214,250 ΑН 257 714 5,239,200 08/24/93 Messina et al. 12/07/93 439 73 5,267,867 Agahdel et al. 250 5,290,970 03/01/94 Currie 174 Andresen et al. 361 699 5,305,184 04/19/94 216 20 08/02/94 Gregoire ам 5,334,279 Lebby et al. 385 53 5,367,593 11/22/94 ΑN 29 848 02/21/95 Gregoire ΑO 5,390,412 5,451,722 09/19/95 Gregoire 174 261 29 Colleran et al. 840 5,579,574 12/3/96 ΑQ 700 5,627,406 05/06/97 Pace 257 714 726 06/30/98 Oureshi 5,774,475 374 104 5,800,060 09/01/98 Speckbrock et al. 324 05/04/99 Khandros et al. 761 5,900,738 ΑU 247 ΑV 5,972,152 10/26/99 Lake et al. 156 174 250 5,998,738 12/07/99 Li et al. AW 174 262 6,005,198 12/21/99 Gregoire AX I DATE CONSIDERED **EXAMINER**

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